

# ULTRA-PRECISION 1:8 FANOUT BUFFER WITH 400mV LVPECL OUTPUTS Precisi AND INTERNAL TERMINATION

### Precision Edge<sup>®</sup> SY58033U

### FEATURES

- Precision 1:8, 400mV LVPECL fanout buffer
- Guaranteed AC performance over temperature and voltage:
  - Clock frequency range: DC to 5.5GHz
  - <80ps t<sub>r</sub> / t<sub>f</sub> times
  - <280ps t<sub>pd</sub>
  - <20ps skew</li>
- Low-jitter performance:
  - <10ps<sub>PP</sub> total jitter (clock)
  - <1ps<sub>RMS</sub> random jitter (data)
- 100k LVPECL compatible outputs
- Fully differential inputs/outputs
- Accepts an input signal as low as 100mV
- Unique input termination and V<sub>T</sub> pin accepts DC-coupled and AC-coupled differential inputs: (LVPECL, LVDS, and CML)
- Power supply 2.5V ±5% or 3.3V ±10%
- Industrial temperature range: -40°C to +85°C
- Available in 32-pin (5mm x 5mm) MLF<sup>®</sup> Package



### Precision Edge®

### DESCRIPTION

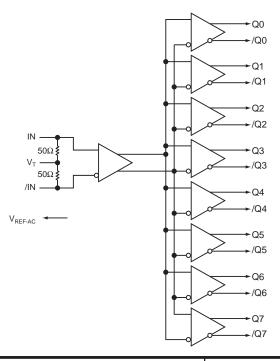
The SY58033U is a 2.5V/3.3V precision, high-speed, fully differential 400mV LVPECL 1:8 fanout buffer. The SY58033U is optimized to provide eight identical output copies with less than 20ps of skew and less than 10ps<sub>pp</sub> total jitter. It can process clock signals as fast as 5.5GHz.

The differential input includes Micrel's unique, 3-pin input termination architecture that allows the SY58033U to directly interface to LVPECL, CML, and LVDS differential signal (ACor DC-coupled) without any level-shifting or termination resistor networks in the signal path. The result is a clean, stub-free, low-jitter solution. The LVPECL (100k temperature compensated) outputs feature a 400mV typical swing into 50ý loads, and provide an extremely fast rise/fall time guaranteed to be less than 80ps.

The SY58033U operates from a 2.5V  $\pm$ 5% supply or 3.3V  $\pm$ 10% supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). Other high-speed 1:8 fanout buffers include the CML SY58031U and the 800mV LVPECL SY58032U. The SY58033U is part of Micrel's high-speed, Precision Edge<sup>®</sup> product line.

All support documentation can be found on Micrel's web site at www.micrel.com.

### FUNCTIONAL BLOCK DIAGRAM

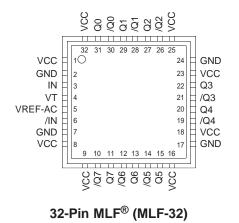


### APPLICATIONS

- All SONET and all GigE clock distribution
- All Fibre Channel clock and data distribution
- Network routing engine timing distribution
- High-end, low-skew multiprocessor synchronous clock distribution

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# PACKAGE/ORDERING INFORMATION



# Ordering Information<sup>(1)</sup>

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58033UMI	MLF-32	Industrial	SY58033U	Sn-Pb
SY58033UMITR <sup>(2)</sup>	MLF-32	Industrial	SY58033U	Sn-Pb
SY58033UMG <sup>(3)</sup>	MLF-32	Industrial	SY58033U with Pb-Free bar-line indicator	Pb-Free NiPdAu
SY58033UMGTR <sup>(2, 3)</sup>	MLF-32	Industrial	SY58033U with Pb-Free bar-line indicator	Pb-Free NiPdAu

#### Notes:

1. Contact factory for die availability. Dice are guaranteed at  $T_A = 25^{\circ}C$ , DC electricals only.

2. Tape and Reel.

3. Pb-Free package recommended for new designs.

# **PIN DESCRIPTION**

Pin Number	Pin Name	Pin Function	
3, 6	IN, /IN	Differential Signal Input: Each pin of this pair internally terminates with 50ý to the V <sub>T</sub> pin. Note that this input will default to an indeterminate state if left open. See "Input Interface Applications" section.	
4	VT	Input Termination Center-Tap: Each input terminates to this pin. The V <sub>T</sub> pin provides center-tap for each input (IN, /IN) to the termination network for maximum interface flexibility. See "Input Interface Applications" section.	
2, 7, 17, 24	GND, Exposed Pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pin.	
1, 8, 9, 16, 18, 23, 25, 32	VCC	Positive Power Supply: Bypass with 0.1µF <sup>TMTM</sup> 0.01µF low ESR capacitors as close to the pins as possible.	
31, 30, 29, 28, 27, 26, 22, 21, 20, 19, 15, 14, 13, 12, 11, 10	Q0, /Q0, Q1, /Q1, Q2, /Q2, Q3, /Q3 Q4, /Q4, Q5, /Q5, Q6, /Q6, Q7, /Q7	400mV LVPECL Differential Output Pairs: Differential buffered output copy of the input signal. The LVPECL output swing is typically 400mV into 50ý. Unused output pairs may be left floating with no impact on jitter. See "LVPECL Output" section.	
5	VREF-AC	Bias Reference Voltage: Equal to V <sub>CC</sub> -1.2V (approx.), and used for AC-coupled applications. See "Input Interface Applications" section. When using V <sub>REF-AC</sub> , bypass with 0.01µF capacitor to V <sub>CC</sub> . Maximum sink/source current is 0.5mA.	

### Absolute Maximum Ratings<sup>(1)</sup>

Power Supply Voltage (V $_{\rm CC}$ )–0.5V to +4.0V
Input Voltage (V_IN) –0.5V to V_CC
Current (V <sub>T</sub> )
Source or sink current on V <sub>T</sub> pin±100mA
Input Current (V <sub>T</sub> )
Source or sink current on IN, /IN±50mA
Current (V <sub>REF</sub> )
Source or sink current on V <sub>REF-AC</sub> <sup>(3)</sup> ±1.5mA
Lead Temperature Soldering (20 sec.)
Storage Temperature Range (T <sub>S</sub> )–65°C to +150°C

# Operating Ratings<sup>(2)</sup>

Power Supply Voltage (V <sub>CC</sub> )	+2.375V to +3.60V
Ambient Temperature Range $(T_A)$	40°C to +85°C
Package Thermal Resistance <sup>(4)</sup>	
MLF <sup>®</sup> (θ <sub>JA</sub> )	
Still-Air	35°C/W
MLF <sup>®</sup> (ψ <sub>JB</sub> )	
Junction-to-Board	20°C/W

# DC ELECTRICAL CHARACTERISTICS<sup>(5)</sup>

 $T_A = -40^{\circ}C$  to +85°C.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>CC</sub>	Power Supply Voltage	2.5V nominal 3.3V nominal	2.375 3.0	2.5 3.3	2.625 3.6	V V
I <sub>CC</sub>	Power Supply Current	V <sub>CC</sub> = max. No. load includes current through 50ý pull-ups.		180	250	mA
V <sub>IH</sub>	Input HIGH Voltage	IN, /IN, Note 6	V <sub>CC</sub> -1.6		V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage	IN, /IN	0		V <sub>IH</sub> –0.1	V
V <sub>IN</sub>	Input Voltage Swing	IN, /IN, see Figure 1a.	0.1		1.7	V
$V_{DIFF_IN}$	Differential Input Voltage Swing  IN0, /IN0 ,  IN1, /IN1	IN, /IN, see Figure 1b.	0.2			V
R <sub>IN</sub>	In-to-V <sub>T</sub> Resistance		40	50	60	ý
V <sub>T IN</sub>	Max. In-to-V <sub>T</sub> (IN, /IN)				1.28	V
V <sub>REF-AC</sub>			V <sub>CC</sub> -1.3	V <sub>CC</sub> -1.2	V <sub>CC</sub> -1.1	V

# LVPECL DC ELECTRICAL CHARACTERISTICS<sup>(5)</sup>

 $V_{CC} = 2.5V \pm 5\%$  or 3.3V  $\pm 10\%$ ;  $R_{L} = 50\%$  to  $V_{CC}-2V$ ;  $T_{A} = -40$ °C to +85°C unless otherwise stated

Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>OH</sub>	Output HIGH Voltage		V <sub>CC</sub> -1.145		V <sub>CC</sub> -0.895	V
V <sub>OL</sub>	Output LOW Voltage		V <sub>CC</sub> -1.545		V <sub>CC</sub> -1.295	V
V <sub>OUT</sub>	Output Voltage Swing	see Figure 1a.	150	400		mV
V <sub>DIFF_OUT</sub>	Differential Voltage Swing	see Figure 1b.	300	800		mV

#### Notes:

2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

3. Due to the limited drive capability, use for input of the same package only.

4. Thermal performance assumes exposed pad is soldered (or equivalent) to the device's most negative potential (GND) on the PCB.  $\psi_{JB}$  uses 4-layer  $\theta_{JA}$  in still-air number unless otherwise stated.

5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

6. V<sub>IH</sub> (min) not lowers than 1.2V.

<sup>1.</sup> Permanent device damage may occur if "Absolute Maximum Ratings" are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to "Absolute Maximum Ratings" conditions for extended periods may affect device reliability.

### AC ELECTRICAL CHARACTERISTICS<sup>(7)</sup>

1/1 = 251/15% or $331/110%$ R	$-50\%$ to $\sqrt{22}$ T $-40$	0°C to +85°C, unless otherwise stated.
$v_{\rm CC} = 2.5 v \pm 5 / 0 0 5.5 v \pm 10 / 0, R_{\rm I}$	$= 500 \text{ to } \text{ v} \text{ CC} - 2 \text{ v}, \text{ T}_{A} = -400 \text{ c}$	$J \cup 10 \pm 00 \cup$ , unless otherwise stated.

Symbol	Parameter		Condition		Min	Тур	Max	Units
f <sub>MAX</sub>	Maximum C	Dperating Frequency	V <sub>OUT</sub> ž 200mV	Clock	5.5			GHz
t <sub>pd</sub>	Propagation	n Delay (IN-to-Q)			130	200	280	ps
t <sub>pd</sub> tempco		Propagation Delay e Coefficient				35		fs/°C
t <sub>SKEW</sub>	Output-to-O	utput Skew (within device)	Note 8			7	20	ps
	Part-to-Part Skew		Note 9				100	ps
t <sub>JITTER</sub>	Clock	Cycle-to-Cycle	Note 10				1	ps <sub>RMS</sub>
		Total Jitter (Clock)	Note 11				10	ps <sub>PP</sub>
		Random Jitter (RJ)	Note 12				1	ps <sub>RMS</sub>
t <sub>r</sub> , t <sub>f</sub>	Output Rise	/Fall Time	20% to 80%, at full output swing.		20	50	80	ps

#### Notes:

7. High frequency AC electricals are guaranteed by design and characterization. All outputs loaded with 50ý to V<sub>CC</sub>-2V, V<sub>IN</sub> ž 100mV.

8. Output-to-output skew is measured between outputs under identical conditions.

- Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs. Part-to-part skew includes variation in t<sub>pd</sub>.
- 10. Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles,  $T_n T_{n-1}$  where T is the time between rising edges of the output signal.
- Total jitter definition: With an ideal clock input of frequency f<sub>MAX</sub>, no more than one output edge in 10<sup>12</sup> output edges will deviate by more than the specified peak-to-peak jitter value.
- 12. Random jitter is measured with a K28.7 comma detect character pattern, measured at 1.25Gbps and 2.5Gbps.

### SINGLE-ENDED AND DIFFERENTIAL SWINGS

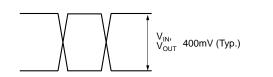


Figure 1a. Single-Ended Voltage Swing

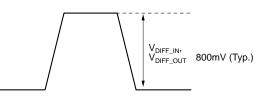
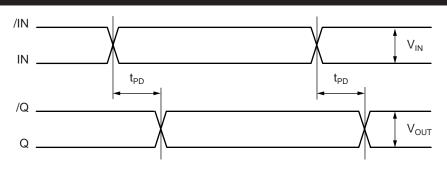


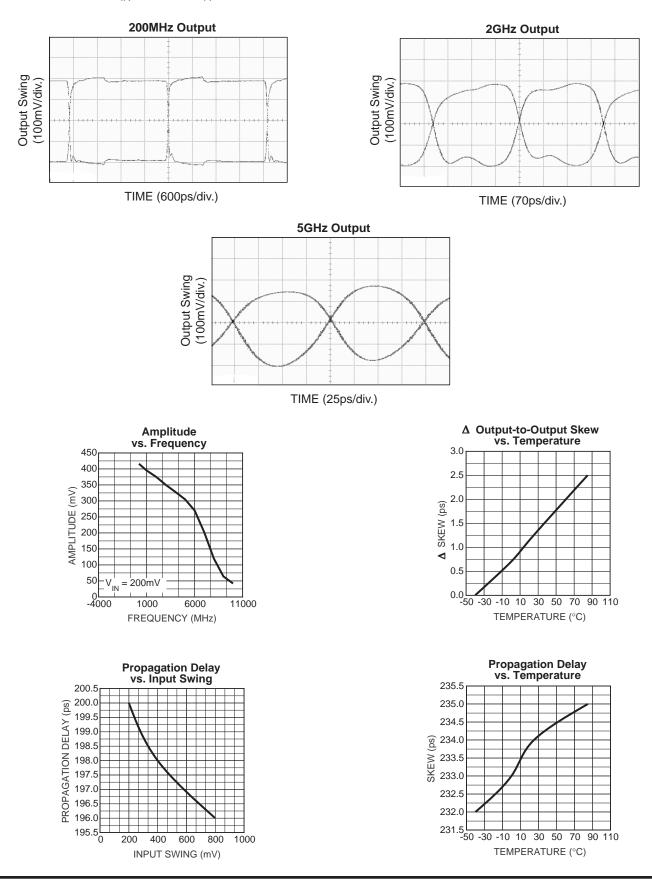
Figure 1b. Differential Voltage Swing

### TIMING DIAGRAM

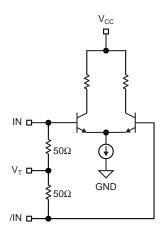


### **TYPICAL OPERATING CHARACTERISTICS**

 $V_{CC}$  = 2.5V, GND = 0,  $V_{IN}$  = 100mV,  $T_A$  = 25°C, unless otherwise stated.

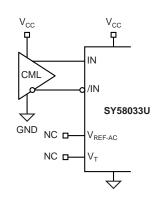


### **INPUT BUFFER**





### **INPUT INTERFACE APPLICATIONS**



# Figure 3a. DC-Coupled CML **Input Interface**

Option: May connect  $V_{\tau}$  to  $V_{cc}$ .

 $V_{CC}$ 

Q

VPEC

GND

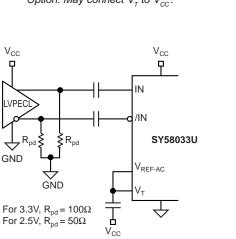


Figure 3d. AC-Coupled LVPECL Input Interface

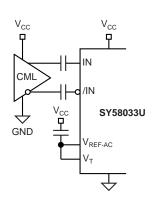


Figure 3b. AC-Coupled CML **Input Interface** 

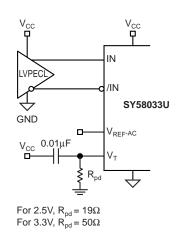


Figure 3c. LVPECL **Input Interface** 

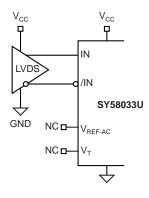


Figure 3e. LVDS **Input Interface** 

### LVPECL OUTPUT

LVPECL has high input impedance, and very low output impedance (open emitter), and small signal swing which results in low electromagnetic interference (EMI). LVPECL is ideal for driving 50ý and 100ý controlled impedance transmission lines. There are several techniques in terminating the LVPECL output, which are the Parallel Termination-Thevenin Equivalent, the Parallel Termination (3-Resistor), and the AC-Coupled Termination. Unused output pairs may be left floating. However, single-ended outputs must be terminated, or balanced.

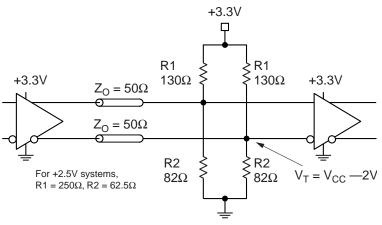
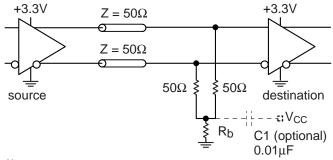


Figure 4. Parallel Termination-Thevenin Equivalent



Notes:

1. Power saving alternative to Thevenin termination.

2. Place termination resistors as close to destination inputs as possible.

3.  $\rm R_b$  resistor sets the DC bias voltage, equal to  $\rm V_T.$ 

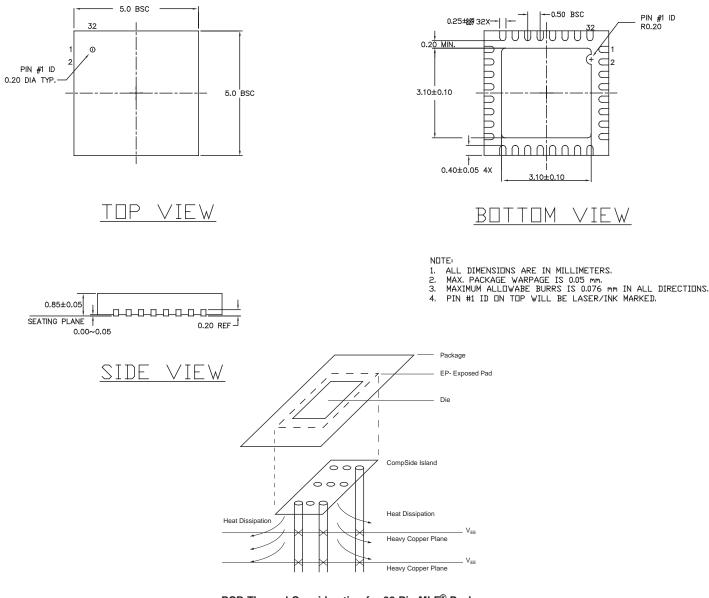
4. For 2.5V systems,  $R_{b}$  = 19 $\Omega,$  For 3.3V systems,  $R_{b}$  = 50 $\Omega$ 

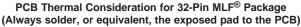
Figure 5. Parallel Termination (3-Resistor)

### **RELATED MICREL PRODUCTS AND SUPPORT DOCUMENTATION**

Part Number	Function	Data Sheet Link			
SY58031U	Ultra-Precision 1:8 Fanout Buffer with 400mV CML Outputs and Internal I/O Termination	http://www.micrel.com/product-info/products/sy58031u.shtml			
SY58032U	Ultra-Precision 1:8 Fanout Buffer with LVPECL Outputs and Internal Termination	http://www.micrel.com/product-info/products/sy58032u.shtml			
SY58033U	Ultra-Precision 1:8 Fanout Buffer with 400mV LVPECL Outputs and Internal Termination	http://www.micrel.com/product-info/products/sy58033u.shtml			
	32-MLF <sup>®</sup> Manufacturing Guidelines Exposed Pad Application Note	www.amkor.com/products/notes_papers/MLF_AppNote_0902.pdf			
	HBW Solutions	http://www.micrel.com/product-info/as/solutions.shtml			

### 32-PIN *Micro*LeadFrame<sup>®</sup> (MLF-32)





#### Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

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